

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination ANNAMANENI ET AL.	
		Examiner Carlos Ortiz-Rodriguez	Art Unit 2125	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-5,751,581	05-1998	Tau et al.	700/115
*	B	US-5,841,660	11-1998	Robinson et al.	700/115
*	C	US-5,889,674	03-1999	Burdick et al.	700/121
*	D	US-6,684,121	01-2004	Lu et al.	700/108
*	E	US-6,748,287	06-2004	Hagen et al.	700/99
*	F	US-6,839,601	01-2005	Yazback et al.	700/97
*	G	US-6,871,113	03-2005	Maxim et al.	700/121
*	H	US-6,959,226	10-2005	Hsieh, Hui-Jye	700/115
*	I	US-7,006,885	02-2006	Chen, Yen-Hung	700/102
*	J	US-2002/0188682	12-2002	Jain et al.	709/205
*	K	US-2003/0236718	12-2003	Yang et al.	705/28
*	L	US-2004/0001619	01-2004	Tai et al.	382/141
*	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Oracle E-Business Suite High-Tech Semiconductor Industry Solutions, Achieving Excellence in Manufacturing and Customer Response Through Oracle Shop Floor Management" (An Oracle White Paper, February 2003).
	V	"Oracle E-Business Suite High-Tech Semiconductor Industry Solution, Key SCM Challenges and Oracle's Strategy/Response", An Oracle White Paper, February 2003.
	W	"A framework for supply chain management in semiconductor manufacturing industry", to Ovacik et al., i2 Technologies, 1995 IEEE.
	X	"eSilicon Delivers ASIC Time to market breakthrough; fables ASIC Company Announces Infrastructure to speed design, manufacture, and delivery of chips", Business Wire, July 24, 2001.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.